



SMP Layer Cleaning

Handling & Cleaning

Gold Pin Contact Set – “SMP Layer”:

- Always handle by the outside edges and avoid touching the top and bottom of the contacts.
- Use compressed air to blow dust and debris from the top and bottom of the contacts prior to use and assembly.
- It is recommended to leave the contacts assembled on the socket as long as possible.

However, if cleaning is necessary after a number of actuations to remove difficult contaminants or solder residue, remove the SMP Layer from the socket, taking note of the orientation with the SM layer, and clean both sides (tips and tails) of the SMP contacts with a fiberglass or bristle brush. Isopropyl alcohol may also be used to clean the SMP layer.

Important: Cleaning using brushes and isopropyl alcohol is for the SMP contact layer only and should never be used on the SM Layer

If cleaning chemicals are required to clean the SMP layer, it must be completely dry prior to installing with the SM layer

- When using a brush to clean the SMP layer, always brush in a sweeping motion across the contacts in one direction and then do the same in the perpendicular direction. Always brush both the top and bottom of the SMP layer and blow off any cleaning debris with compressed air prior to use and assembly.

Important: Be sure no cleaning debris is picked up by the SM Layer

